

Lead-Free Solder Bar

Model: PF604-B

Rev.2012/10/15 Ver.08-00

— Specification —

Item	Specification
Alloy Composition	Sn/Cu0.7
Appearance	Bright and shiny surface finishes.
Shape	Bar.
Density	Approx. 7.3 g/cm ³ (20 °C)
Melting Point	Approx. 227~228°C.
Packaging	Net weight Approx. 20kg/carton.
Feature	Produced by pure tin and copper. Impurities are lowed to the minimum.
Application	For wave soldering process.
Reference Standard	JIS-Z-3282
Storage and Handling	Storage must be in a dry, non-corrosive and shine environment.
Shelf life	Shelf life is 2 years from date of manufacture.

— Alloy Composition —

Sn	Cu	Ni	Pb	Sb	Bi	Cd	Au	In	Ag	Al	As	Fe	Zn
REM.	0.5~ 0.9	0~ 0.01	0.05 Max	0.05 Max	0.10 Max	0.002 Max	0.05 Max	0.10 Max	0.10 Max	0.001 Max	0.03 Max	0.02 Max	0.001 Max

All alloy of SHENMAO' products were to conform to SONY Green Partner and comply RoHS requirement.

(wt %)

Contact Information

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BRANCHES:

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